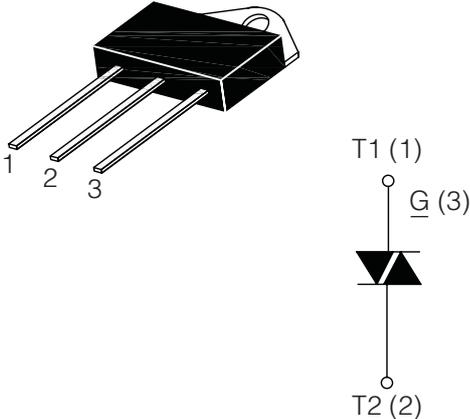


INSULATED HIGH COMMUTATION TRIAC

<p>INSULATED TO3P</p> 	<p>On-State Current 40 Amp</p>	<p>Gate Trigger Current ≤ 50 mA (16)</p>
	<p>Off-State Voltage 600 V ÷ 800 V</p>	
<p>* Standard current TRIAC * Low thermal resistance with clip bounding * Low thermal resistance isolation ceramic for FT....P</p> <p>This series of TRIACs uses a high performance PNPN technology.</p> <p>These parts are intended for general purpose AC switching applications with highly inductive loads. The FT....P series provides an isolated tab (rated at 2500 Vrms).</p>		

Absolute Maximum Ratings, according to IEC publication No. 134

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
$I_{T(RMS)}$	RMS On-state Current (full sine wave)	All Conduction Angle, $T_c = 80\text{ °C}$	40	A
I_{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz ($t = 16.7\text{ ms}$)	420	A
I_{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz ($t = 20\text{ ms}$)	400	A
I^2t	Fusing Current	$t_p = 10\text{ ms}$, Half Cycle	1000	A ² s
I_{GM}	Peak Gate Current	20 μs max. $T_j = 125\text{ °C}$	8	A
$P_{G(AV)}$	Average Gate Power Dissipation	$T_j = 125\text{ °C}$	1	W
di/dt	Critical rate of rise of on-state current	$I_G = 2 \times I_{GT}$, $t_r \leq 100\text{ ns}$ $f = 120\text{ Hz}$, $T_j = 125\text{ °C}$	50	A/ μs
T_j	Operating Temperature		(-40 +125)	°C
T_{stg}	Storage Temperature		(-40 +150)	°C
T_{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER	VOLTAGE		Unit
		M	N	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	600	800	V

INSULATED HIGH COMMUTATION TRIAC

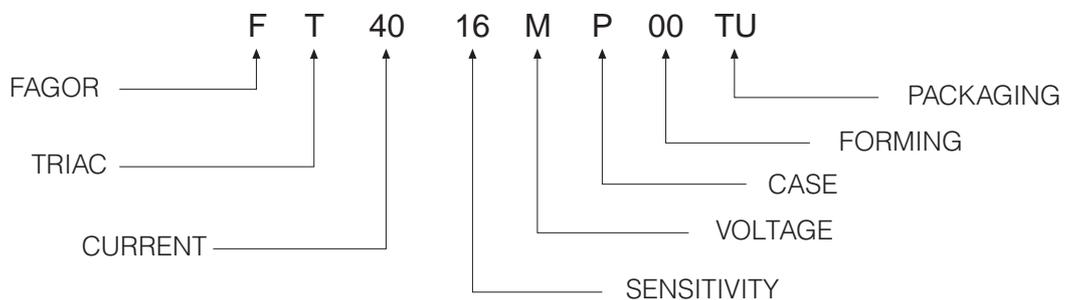
Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	Quadrant		SENSITIVITY	Unit
					16	
$I_{GT}^{(1)}$	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 33\Omega, T_j = 25^\circ C$	Q1÷Q3	MAX	50	mA
V_{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 33\Omega, T_j = 25^\circ C$	Q1÷Q3	MAX	1.3	V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 K\Omega, T_j = 125^\circ C$	Q1÷Q3	MIN	0.2	V
$I_H^{(2)}$	Holding Current	$I_T = 100 mA, \text{Gate open}, T_j = 25^\circ C$		MAX	80	mA
I_L	Latching Current	$I_G = 1.2 I_{GT}, T_j = 25^\circ C$	Q1, Q3	MAX	80	mA
			Q2	MAX	160	mA
$dV/dt^{(2)}$	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}, \text{Gate open}$ $T_j = 125^\circ C$		MIN	500	V/ μs
$V_{TM}^{(2)}$	On-state Voltage	$I_{TM} = 60 \text{ Amp}, t_p = 380 \mu s, T_j = 25^\circ C$		MAX	1.55	V
$V_{t(o)}^{(2)}$	Threshold Voltage	$T_j = 125^\circ C$		MAX	0.85	V
$r_d^{(2)}$	Dynamic resistance	$T_j = 125^\circ C$		MAX	10	m Ω
I_{DRM}/I_{RRM}	Off-State Leakage Current	$V_D = V_{DRM}, T_j = 125^\circ C$		MAX	5	mA
		$V_R = V_{RRM}, T_j = 25^\circ C$		MAX	20	μA
$R_{th(j-c)}$	Thermal Resistance Junction-Case	for AC 360° conduction angle			0.9	$^\circ C/W$

(1) Minimum I_{GT} is guaranteed at 5% of I_{GT} max.

(2) For either polarity of electrode MT2 voltage with reference to electrode MT1.

PART NUMBER INFORMATION



INSULATED HIGH COMMUTATION TRIAC

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

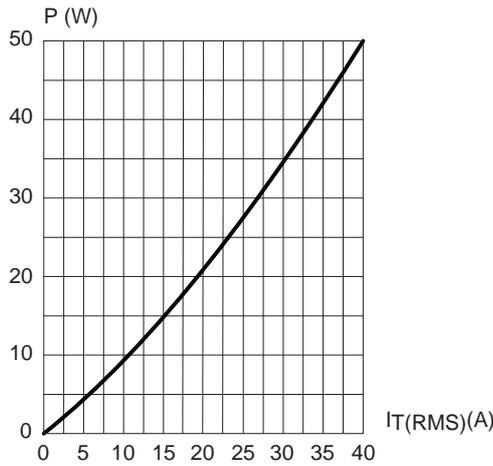


Fig. 2: RMS on-state current versus case temperature (full cycle).

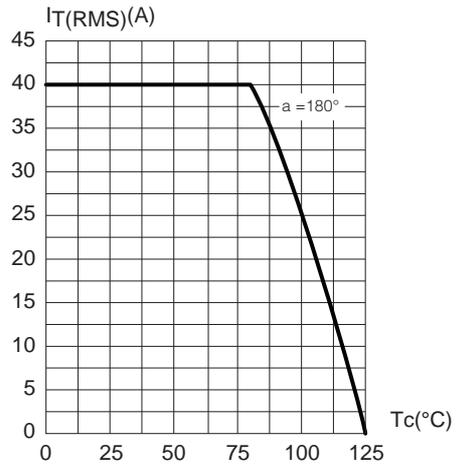


Fig. 3: On-state characteristics (maximum values)

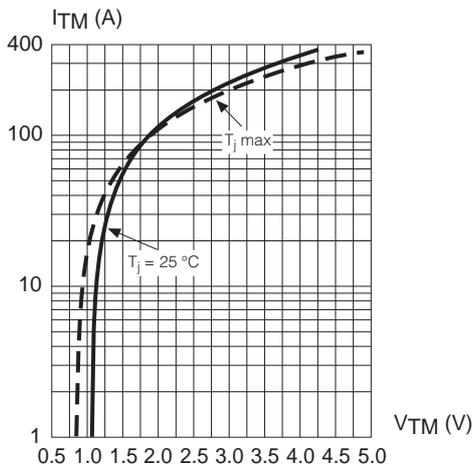


Fig. 4: Surge peak on-state current versus number of cycles

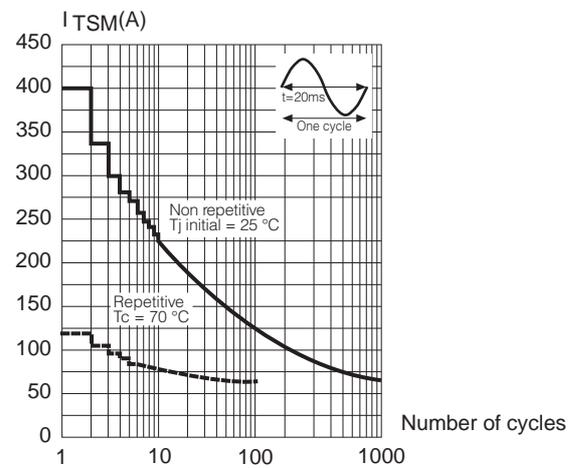


Fig. 5: Non repetitive surge peak on-state current for a sinusoidal pulse with width: $t_p < 10$ ms, and corresponding value of I^2t .

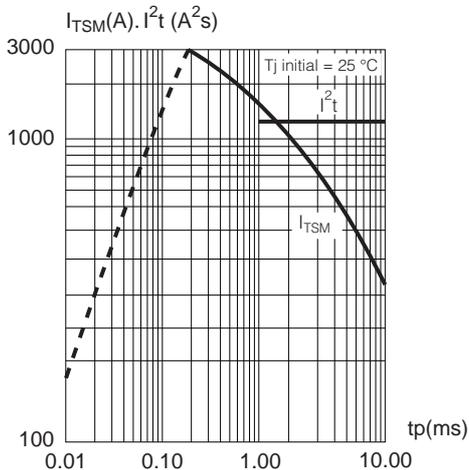
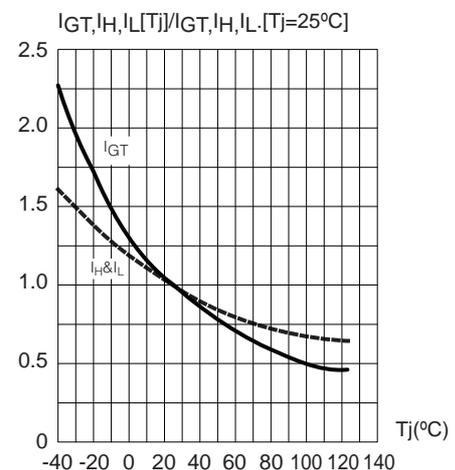
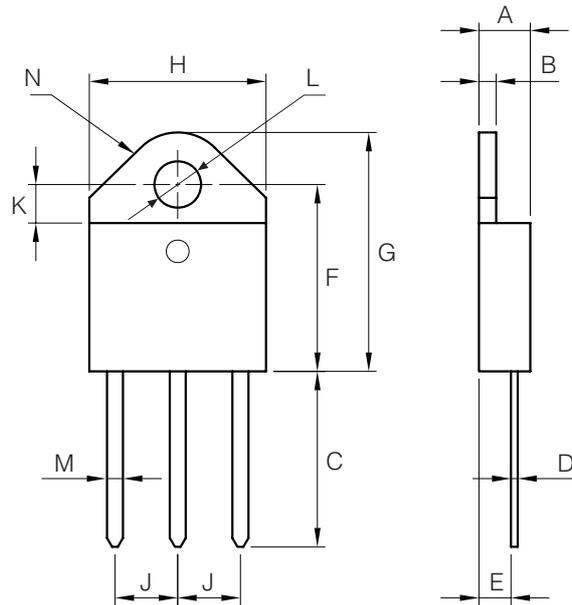


Fig. 7: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values)



INSULATED HIGH COMMUTATION TRIAC

PACKAGE MECHANICAL DATA: INSULATED TO3P



DIMENSIONS (mm)

	A	B	C	D	E	F	G	H	J	K	L	M	N
MAX	4.6	1.55	15.6	0.7	2.9	16.5	21.1	15.5	5.65	3.65	4.17	1.40	
TYP													4.60
MIN	4.4	1.45	14.35	0.5	2.7	15.8	20.4	15.1	5.4	3.4	4.08	1.20	

Mounting Torque

1 N.m

(*) Limiting values and life support applications, see Web page.